

Title (en)

Method for manufacturing panels containing conducting tracks

Title (de)

Verfahren zum Herstellen von Leiterbahnen enthaltenden Paneelen

Title (fr)

Procédé pour la fabrication de panneaux contenant des pistes conductrices

Publication

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Application

EP 07722065 A 20070319

Priority

DE 2007000505 W 20070319

Abstract (en)

[origin: WO2008113304A1] The invention relates to a panel device (100) comprising at least one carrier layer (110; 120) with an upper (111; 121) and a lower surface (112; 122) and a layer (130) adjacent to the lower surface (112; 122) of the carrier layer (110; 120) and made of a porous, electrically insulating material. The usability as carrier element and/or as a protective cover for electric lines to be installed is achieved by one or more electric conductor tracks (150) being arranged between the at least one carrier layer (110; 120) and the layer (130) made of a porous, electrically insulating material. The layer made of porous material has an anisotropic honeycomb structure with long, narrow honeycomb tubes (131), wherein the longitudinal axis of the tubes (131) is oriented substantially perpendicular to the lower surface (112; 122) of the carrier layer (110; 120).

IPC 8 full level

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CPC (source: EP)

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Citation (search report)

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